



Material Content Data Sheet



Sales Product Name	TLF4277EL			Issued	28. August 2013			
MA#	MA000970660							
Package	PG-SSOP-14-2			Weight*	83.81 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.604	5.49	5.49	54934	54934
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		411	
	non noble metal	iron	7439-89-6	0.689	0.82		8221	
wire	non noble metal	copper	7440-50-8	27.978	33.38	34.25	333820	342555
	noble metal	gold	7440-57-5	0.106	0.13	0.13	1270	1270
	encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1116
encapsulation	plastics	epoxy resin	-	4.301	5.13		51321	
	inorganic material	silicondioxide	60676-86-0	42.358	50.56	55.80	505401	557838
leadfinish	non noble metal	tin	7440-31-5	0.976	1.16	1.16	11647	11647
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9159	9159
glue	plastics	epoxy resin	-	0.473	0.56		5649	
	noble metal	silver	7440-22-4	1.420	1.69	2.25	16948	22597
*deviation	< 10%			Sum in total:		100,00		1000000

Important Remarks:

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